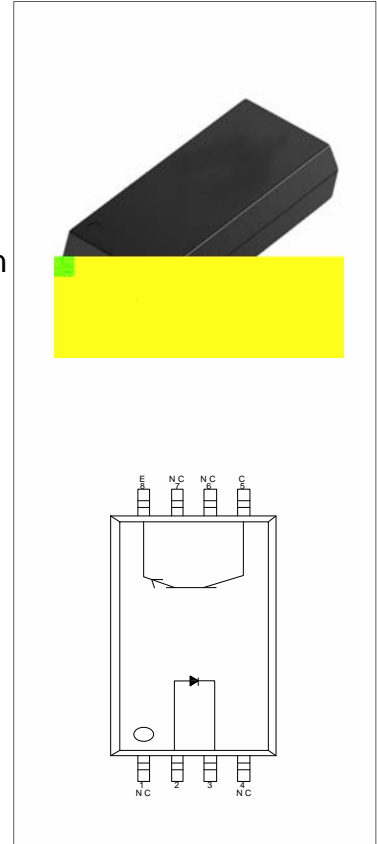


DESCRIPTION:

The products are transistor opto-couplers in a plastic WSOP8 package. The device which is infrared LED chip and photo-transistor chip is assembled on lead frame, in order to change the electricity-light-electricity. The products are widely used in transmission and conversion of digital logic, power control and switch, electric insulation and impedance conversion between circuits systems.



MAIN FEATURES

High isolation 7500 VRMS

CTI 600

Operating temperature range -55°C to 110°C

RoHS & REACH Compliance

HBM: H3A; MM: M4; CDM:C3

CQC approved

VDE approved

UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_C	75	mW
Output	Collector-emitter Voltage	V_{CEO}	80	V
	Emitter-collector Voltage	V_{ECO}	7	V
	Collector Current	I_C	50	mA
	Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	2	mW
Isolation Voltage		V_{iso}	7500	Vrms
Operating Temperature		T_{opr}	-55~+110	
Junction Temperature		T_j	125	

Ltd.

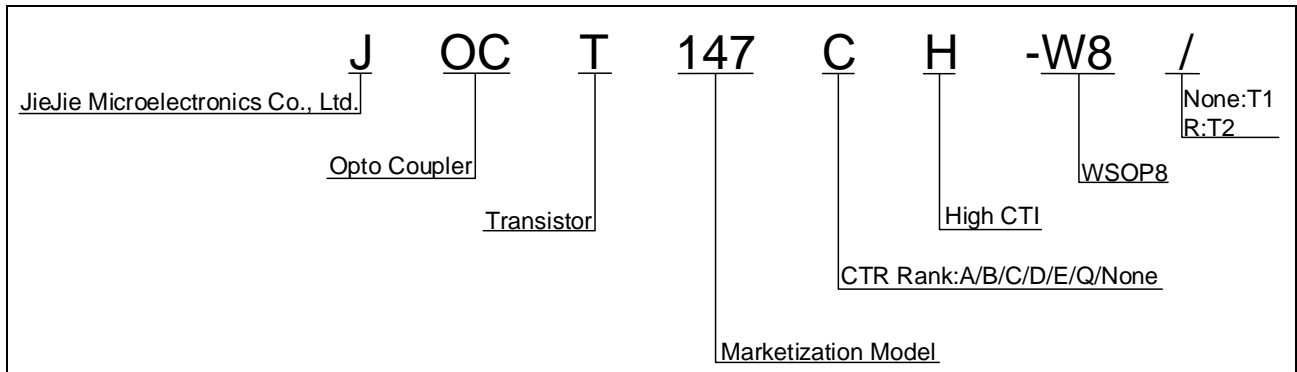
Unit

V

μ A

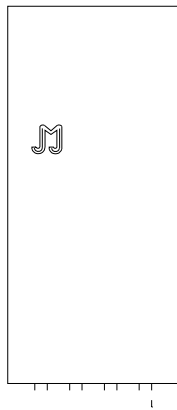
CTR

ORDERING INFORMATION



Packing Quantity	
Option	Quantity
None/R	1200 Units/Reel

MARKING



Test Circuits

FIG.12: Test Circuits of Turn On Time

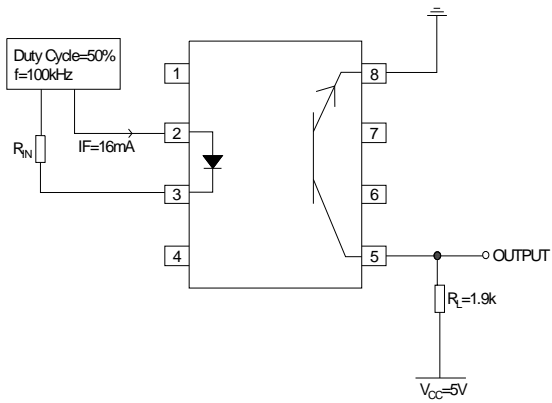
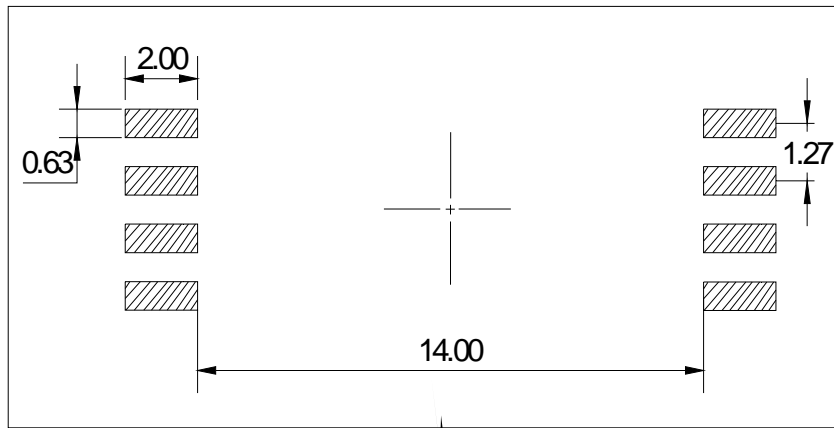


FIG.13: Waveforms of Turn On Time

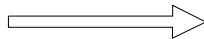
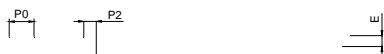
Package Dimension (Unit: mm)

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A						
B						
C						
D						
E						
F						
G						
H						
I						
J						

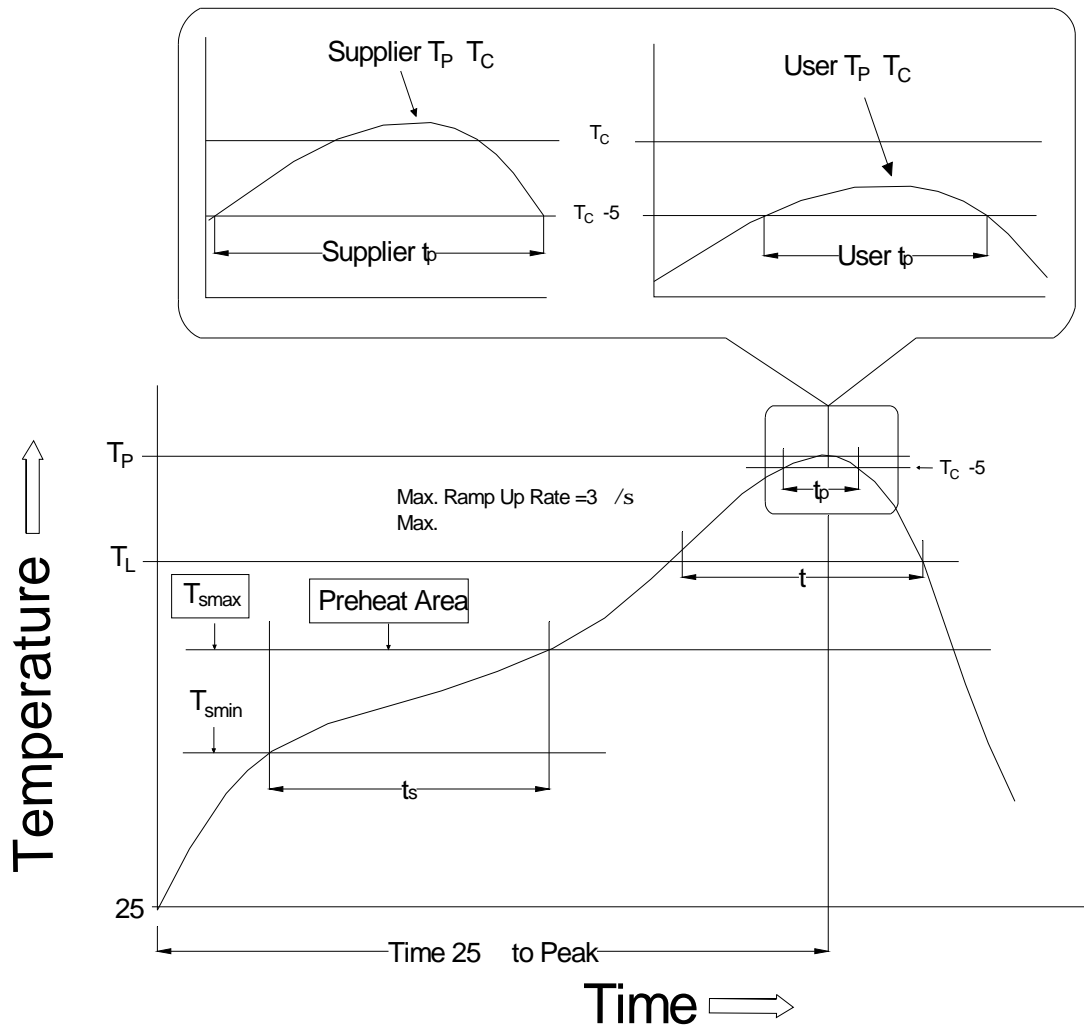
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



REFLOW INFORMATION




Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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